


FORM PTO-1449 (Colb)	ATTY DOCKET NO. 206,407	SERIAL NUMBER 10/750,716
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS' INFORMATION STATEMENT	APPLICANT Yossi SHACHAM-DIAMAND et al.	EXAMINER <del>AWA</del> Klemanski
	FILING DATE January 2, 2004	GROUP ART UNIT <del>1742</del> 1755

## U.S. PATENT DOCUMENTS

Examiner's Initials		DOCUMENT NO.	DATE	NAME	CLASS	SUB	FILING DATE
<i>AK</i>	AA	5,695,810	12-1997	Dubin, et al.	438	643	
<i>AK</i>	AB	5,674,787	10-1997	Zhao, et al.	438	627	
<i>AK</i>	AC	4,209,331	06-1980	Kukanskis, et al.	106	1.23	
<i>AK</i>	AD	4,150,171	04-1979	Feldstein	427	558	

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB	TRANS- LATION
	AE						
	AF						

## OTHER ART (Including Author, Bills, Pertinent Pages, Etc.)

<i>AK</i>	AG	P.C. Andricacos, Damascene Copper Electroplating for Chip Interconnect, IBM J. Res. Develop 42 (1998) 567-573, <u>no month available.</u>
<i>AK</i>	AH	Y. Shacham-Diamand, V. Dubin, and M. Angyal, Copper Electroless deposition for ULSI, Thin Solid Films, 262, (1995) 93-103, <u>no month available.</u>
<i>AK</i>	AI	Vashkjalas A., Demontaine O. Study of Cu electroless deposition process using NaBH <sub>4</sub> as a reducing agent, Lithuanian Academy of Sciences publication, series B, Vol. 4(95), pp.11-16, 1976, <u>no month available.</u>
<i>AK</i>	AJ	Molenaar A., J. of the Electrochem. Soc., 1982 Vol. 129, N 9, p.1917-1921, <u>no month available.</u>
<i>AK</i>	AK	Shalkauskas M., Vashkjalas A. Electroless deposition of metals on plastics, L., J. Chemistry, 1985, pp. 95-113, <u>no month available.</u>
<i>AK</i>	AL	Tetsuya Ogura, M. Malcomson, Q. Fernando, Mechanism of Copper Deposition in Electroless plating, Langmuir 1990, 6, pp.1709-1710, <u>no month available.</u>

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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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	AG	F.P. Pearlstein and R.F. Weightman, Electroless Deposition of Silver Using Dimethylamine Borane, Plating, February 1974, pp.154-157.
	AH	Y. Shacham-Diamand, and V. Dubin, J. of Microelectronics Engineering, 33, pp. 47-58, <del>1997</del> 1997.
	AI	Yosi Shacham-Diamand and Sergey Lopatin, Journal of Microelectronics Engineering, Vol. 37/38, pp. 77-88, 1997, no month available.
	AJ	E. Gileadi, Electrode Kinetics, VCH Publishers, New York 1993, no month available.
	AK	E. Podlaha and D. Landolt, A Mathematical Model Describing the Electrodeposition of Ni-Mo Alloys, J. of the Electrochem. Soc., Vol. 143, pp.893-899, 1996, no month available.
	AL	E. Podlaha and D. Landolt, Molybdenum Alloys with Nickel, Cobalt and Iron, J. of the Electrochem. Soc., Vol. 144, pp.1672-1680, 1997, no month available.

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	AE	E. Podlaha and D. Landolt, An Experimental Investigation of Ni-Mo Alloys, J. of the Electrochem. Soc., Vol. 143, pp. 885-892, 1996, no month available.
	AF	Y. Shacham-Diamand and Y. Sverdlov, Electroless Cu alloys for ULSI applications, in Proceedings of the Advanced Metallization Conference 2001 (AMC 2001), p.67-72, Montreal, Canada, 8-11 October 2001.
	AG	Y. Shacham-Diamand, A. Inberg, Y. Sverdlov and N. Croitoru, Electroless Silver and Silver with Tungsten Thin Films for Microelectronics and Microelectromechanical System Applications, J. of the Electrochemical Society, 147 (9) 3345-3349 (2000) 1/2000.
	AH	K.M. Gorbunova, A.A. Nikiforova, G.A. Sadakov, V.P. Moiseev, M.V. Ivanov, "Physical-chemical origins of chemical cobalt deposition", "Science" publication, Moscow, pp.195-201, 1974, no month available.
	AI	F. Ajogin, M. Belenki, I. Gall, "Galvanotechnology", "Metallurgy" publication, Moscow, pp.170-178, 538-540, 1987, no month available.
	AJ	Y. Shacham-Diamand, A. Inberg, Y. Sverdlov, V. Bogush, N. Croitoru, H. Moscovich, A. Freeman, Electroless process for micro- and nanoelectronics, J. Electrochimica Acta 48 (2003) 2987-2996, no month available.
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